



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Yoshino, et al.**

Serial No.: **09/909,013**

Filed: **07/19/2001**

For: **Semiconductor Package Insulation Film and
Manufacturing Method Thereof**

Docket No.: **TI-29448**

Examiner: **Geyer, Scott**

Art Unit: **2829**

Conf. No.: **8724**

TRANSMITTAL OF FORMAL DRAWINGS

Assistant Commissioner For Patents
Attn: Official Drafts Person
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with
the U.S. Postal Service as First Class Mail in an envelope addressed
to: Assistant Commissioner For Patents, Washington, DC 20231.


Elizabeth Austin

10/3/2002
Date

Dear Sir:

Submitted herewith are 8 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional
fee is necessary.

Respectfully submitted,



Michael K. Skrehot
Attorney for Applicants
Reg. No.: 36,682

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(972) 917-5653